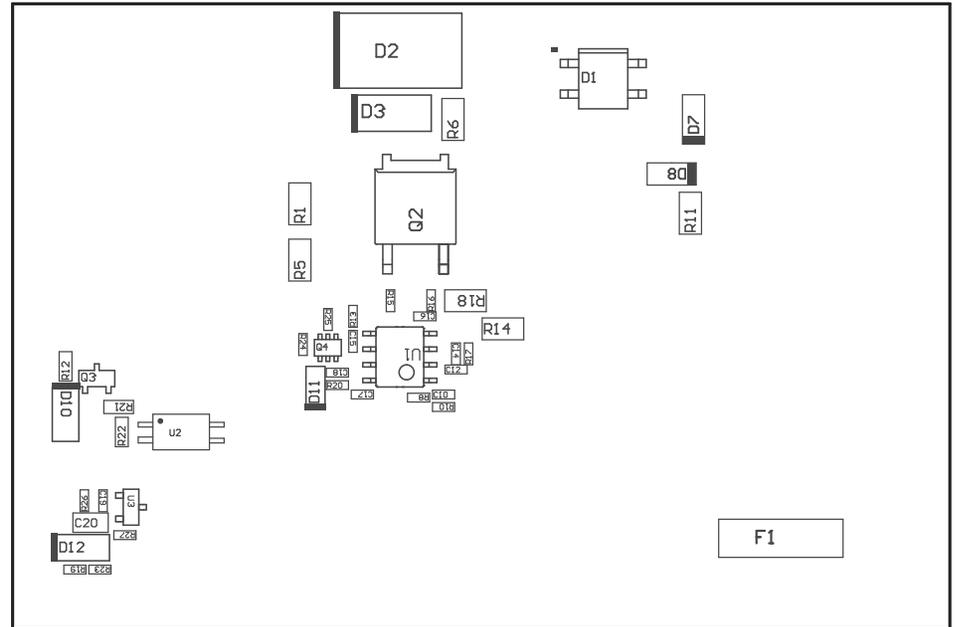


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP11155	REV: B	SUN REV: Not In VersionControl
	TID #:		
PLOT NAME = Top Assembly Drawing	GENERATED : 7/14/2015	10:38:57 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP11155	REV: B	SUN REV: Not In VersionControl
	TID #:		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 7/14/2015	10:38:58 AM	TEXAS INSTRUMENTS

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